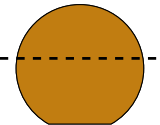


#1

Polished silicon wafer.

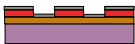
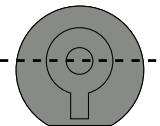


#2

Spin coating first layer of polyimide.

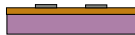
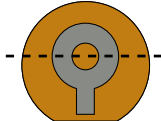


#3

Spin coating of **negative** resist. Patterning with Mask 1 (Metal).

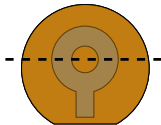
#4

Evaporation of Platinum.



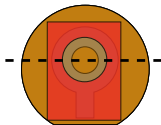
#5

Lift-off.

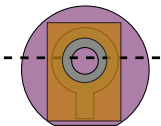


#6

Spin coating of second layer of polyimide.



#7

Spin coating of **positive** resist. Patterning of Mask 2 (PI).

#8

Reactive Ion Etching of PI. Release by peeling.